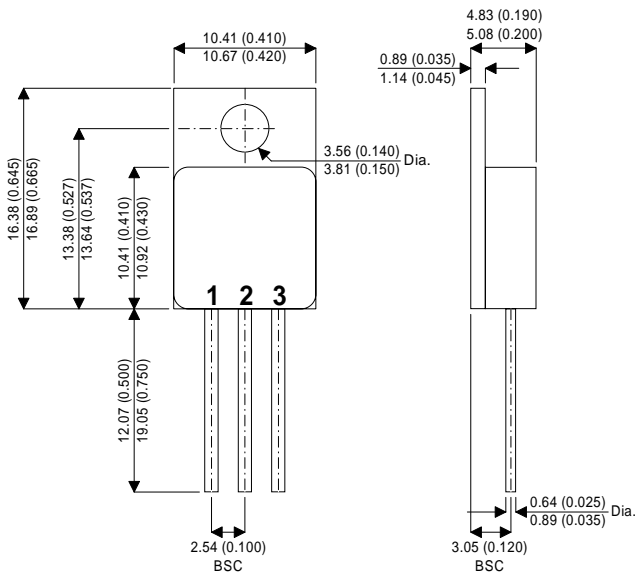


**MECHANICAL DATA**

Dimensions in mm(inches)

**N-CHANNEL  
ENHANCEMENT MODE  
TRANSISTOR**



**TO-257AB Metal Package**

Pin 1 – Gate      Pin 2 – Drain      Pin 3 – Source

$V_{(BR)DSS}$       **200V**  
 $I_{D(A)}$             **14A**  
 $R_{DS(on)}$          **0.16Ω**

**FEATURES**

- TO257AB HERMETIC PACKAGE FOR HIGH RELIABILITY APPLICATIONS
- SCREENING OPTIONS AVAILABLE
- SIMPLE DRIVE REQUIREMENTS

**ABSOLUTE MAXIMUM RATINGS** ( $T_{case} = 25^{\circ}C$  unless otherwise stated)

$V_{DS}$	Drain – Source Voltage		200V
$V_{GS}$	Gate – Source Voltage		±20V
$I_D$	Continuous Drain Current	$T_C = 25^{\circ}C$	14A
		$T_C = 100^{\circ}C$	8.5A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>		56A
$P_D$	Power Dissipation	$T_C = 25^{\circ}C$	60W
		$T_C = 100^{\circ}C$	23W
$T_J, T_{stg}$	Operating and Storage Temperature Range		-55 to 150°C
$T_L$	Lead Temperature ( <sup>1</sup> / <sub>16</sub> " from case for 10 sec.)		300°C

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>STATIC ELECTRICAL RATINGS</b>					
$BV_{(BR)DSS}$ Drain–Source Breakdown Voltage	$V_{GS} = 0$ $I_D = 250\mu\text{A}$	200			V
$V_{GS(th)}$ Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250\mu\text{A}$	2		4	V
$I_{GSS}$ Gate – Body Leakage	$V_{DS} = 0$ $V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
$I_{DSS}$ Zero Gate Voltage Drain Current	$V_{DS} = 160\text{V}$ $V_{GS} = 0$			25	$\mu\text{A}$
	$T_J = 125^\circ\text{C}$			250	
$I_{D(on)}$ On–State Drain Current <sup>1</sup>	$V_{DS} = 10\text{V}$ $V_{GS} = 10\text{V}$	14			A
$R_{DS(on)}$ Static Drain – Source On–State Resistance <sup>1</sup>	$V_{GS} = 10\text{V}$ $I_D = 8.5\text{A}$		0.14	0.16	$\Omega$
	$T_J = 125^\circ\text{C}$		0.25	0.30	
$g_{fs}$ Forward Transconductance <sup>1</sup>	$V_{DS} = 15\text{V}$ $I_{DS} = 8.5\text{A}$	5.0			S
<b>DYNAMIC CHARACTERISTICS</b>					
$C_{iss}$ Input Capacitance	$V_{GS} = 0$		1550		$\text{pF}$
$C_{oss}$ Output Capacitance	$V_{DS} = 25\text{V}$		500		
$C_{rss}$ Reverse Transfer Capacitance	$f = 1\text{MHz}$		220		
$Q_g$ Total Gate Charge <sup>2</sup>	$V_{DS} = 0.5 \times V_{(BR)DSS}$ $V_{GS} = 10\text{V}$ $I_D = 14\text{A}$	30	44	77	$\text{nC}$
$Q_{gs}$ Gate Source Charge <sup>2</sup>		4.6	10	15	
$Q_{gd}$ Gate Drain Charge <sup>2</sup>		13	26	35	
$t_{d(on)}$ Turn–On Delay Time <sup>2</sup>	$V_{DD} = 100\text{V}$ $I_D = 14\text{A}$		10	30	$\text{ns}$
$t_r$ Rise Time <sup>2</sup>	$V_{GEN} = 10\text{V}$		60	100	
$t_{d(off)}$ Turn–Off Delay Time <sup>2</sup>	$R_L = 7.1\Omega$		30	80	
$t_f$ Fall Time <sup>2</sup>	$R_G = 4.7\Omega$		40	95	
<b>SOURCE – DRAIN DIODE CHARACTERISTICS</b>					
$I_S$ Continuous Current				114	A
$I_{SM}$ Pulse Current <sup>3</sup>				56	
$V_{SD}$ Forward Voltage	$I_F = I_S$ $V_{GS} = 0$			2.0	V
$t_{rr}$ Reverse Recovery Time	$I_F = I_S$		150	650	ns
$Q_{rr}$ Reverse Recovery Charge	$di_F/dt = 100\text{A}/\mu\text{s}$		0.5		$\mu\text{C}$

<sup>1</sup>Pulse test : Pulse Width < 300 $\mu\text{s}$  ,Duty Cycle < 2%

<sup>2</sup>Independent of Operating Temperature

<sup>3</sup>Pulse width Limited by maximum Junction Temperature

**THERMAL RESISTANCE CHARACTERISTICS**

Parameter	Min.	Typ.	Max.	Unit
$R_{thJC}$ Thermal resistance Junction-Case			2.1	
$R_{thJA}$ Thermal resistance Junction-ambient			80	K/W
$R_{thCS}$ Thermal resistance Junction-ambient		1.0		